

(Amended) ~~52~~ 30. The ceramic/metal substrate according to claim ~~53~~,  
wherein at least one of the substrate areas comprise single  
substrates.

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~~33~~ (Amended) ~~31~~ 31. The ceramic/metal substrate according to claim ~~53~~,  
wherein the width of the edge reduction or of the reduced metal  
mass area is approximately 0.2 to 6 mm.

~~34~~ (Amended) ~~32~~ 32. The ceramic/metal substrate according to claim ~~53~~,  
wherein at least one outer metal surface that is provided for on  
at least one surface of the ceramic layer at least along one edge  
of the ceramic/metal substrate, and by at least one predetermined  
break line between the at least one outer metal surface and  
adjacent substrate areas, whereby the at least one outer metal  
surface has an edge reduction along the predetermined break line.

~~35~~ (Amended) ~~33~~ 33. The ceramic/metal substrate according to claim ~~53~~,  
wherein an edge having the edge reduction has a distance from the  
adjacent predetermined break line or a plane of the predetermined  
break line that is considerably less than 1 mm.

~~36~~ (Amended) ~~34~~ 34. The ceramic/metal substrate according to claim ~~53~~,  
wherein edges with the edge reduction have a distance from the  
respective predetermined break line of approximately 0.05 to 1  
mm.

~~37~~ (Amended) ~~35~~ 35. The ceramic/metal substrate according to claim ~~53~~,  
wherein the textured or structured metalizations, or metal

surfaces formed by these, have a thickness of between approximately 0.15 to 1 mm.

(Amended) ~~56~~ 6. The ceramic/metal substrate according to claim ~~53~~, wherein the edge reduction is formed by beveling of the respective edge, the beveling forms an angle smaller than 45° with a plane of the ceramic layer.

(Amended) ~~57~~ 7. The ceramic/metal substrate according to claim ~~53~~, wherein the edge reduction is formed by hollows or depressions in a material of the metal surface.

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~~10~~ 10. The ceramic/metal substrate according to claim ~~57~~, wherein the hollows or depressions are formed continuously, and extend to a surface side of the ceramic layer adjacent to the metal surface.

~~11~~ 11. The ceramic/metal substrate according to claim ~~57~~, wherein the hollows or depressions are formed in such a way that metal from the metal surface remains on the surface side of the ceramic layer adjacent to the metal surface.

~~12~~ 12. (Amended) The ceramic/metal substrate according to claim ~~53~~, wherein the edge reduction is formed by a number of hole-like depressions that are arranged as a row of holes.

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~~13~~ 13. The ceramic/metal substrate according to claim ~~50~~, wherein outer and inner depressions form an outer and a second inner row of holes.

~~19~~ 42. The ceramic/metal substrate according to claim ~~40~~,  
wherein the depressions have a diameter of approximately 0.5 to  
0.6 mm.

~~15~~ 43. The ceramic/metal substrate according to claim ~~40~~,  
wherein the depressions forming a single row of holes have a  
diameter of 0.5 mm, with a width of the edge reduction of  
approximately 0.8 mm and with a distance of the edge from the  
predetermined break line of approximately 0.5 mm.

~~16~~ 44. The ceramic/metal substrate according to claim ~~40~~,  
wherein the several rows of holes of the outer row of holes have  
a diameter that is larger than a diameter of the depressions of  
the inner row of holes, whereby the diameter of the depressions  
of the outer row of holes is approximately 0.6mm and the diameter  
of the depressions of the inner row of holes is approximately 0.4  
mm and the width of the edge reduction is approximately 1.4 mm.

~~17~~ (Amended) 45. The ceramic/metal substrate according to claim ~~53~~,  
wherein the edge reduction is formed by a groove-shaped  
depression.

~~18~~ (Amended) 46. The ceramic/metal substrate according to claim ~~53~~,  
wherein the edge reduction is formed by a graduation in at least  
one partial area.

~~19~~ (Amended) 47. The ceramic/metal substrate according to claim ~~40~~,  
wherein at least in an area of the single substrate on both  
surfaces of the ceramic layer at least one metal surface is  
provided for and that the at least one metal surface has, on a  
first surface area, on a bottom of the ceramic/metal substrate,  
an edge distance from the adjacent predetermined break line or

its plane which edge distance is smaller than the edge distance of the metal surfaces on the second surface area, on a top of the ceramic/metal substrate.

(Amended) 48. The ceramic/metal substrate according to claim 53,  
wherein with several substrate areas or single substrates arranged in several rows, two groups of crossing predetermined break lines are formed.

(Amended) 49. The ceramic/metal substrate according to claim 53,  
wherein on at least one surface area of the ceramic/metal substrate, all edges of the metal surfaces adjacent to a predetermined break line are provided with edge reduction.

(Amended) 50. The ceramic/metal substrate according to claim 53,  
wherein the metal surfaces on at least one surface area of the ceramic layer has no edge reduction on edges that are adjacent to a group of predetermined break lines.

(Amended) 51. The ceramic/metal substrate according to claim 50,  
wherein the single substrates are not provided with components.

(Amended) 52. The ceramic/metal substrate according to claim 50,  
wherein the single substrates formed by substrate areas are provided with electric components.

(New) 53. A ceramic/metal substrate, comprising a ceramic layer forming at least two substrate areas connected to each other as one piece and joining each other on at least one predetermined break line provided for in the ceramic layer, metal surfaces on at least one side of the ceramic layer, said

(Amended) 30. The ceramic/metal substrate according to claim [27] 53, wherein at least [part] one of the substrate areas [are] comprise single substrates.

(Amended) 31. The ceramic/metal substrate according to claim [27] 53, wherein the width [(a)] of the edge reduction or of the reduced metal mass area is approximately 0.2 to 6 mm.

(Amended) 32. The ceramic/metal substrate according to claim [27] 53, wherein at least one outer metal surface that is provided for on at least one surface of the ceramic layer at least along one edge of the ceramic/metal substrate, and by at least one predetermined break line between the at least one outer metal surface and adjacent substrate areas, whereby the at least one outer metal surface has an edge reduction along the predetermined break line.

(Amended) 33. The ceramic/metal substrate according to claim [27] 53, wherein an edge having the edge reduction has a distance [(d<sub>1</sub>, d<sub>2</sub>)] from the adjacent predetermined break line or a plane [(SE)] of the predetermined break line that is considerably less than 1 mm.

(Amended) 34. The ceramic/metal substrate according to claim [27] 53, wherein edges with the edge reduction have a distance from the respective predetermined break line of approximately 0.05 to 1 mm.



(Amended) 35. The ceramic/metal substrate according to claim [28] 53, wherein the textured or structured metalizations, or metal surfaces formed by these, have a thickness of between approximately 0.15 to 1 mm.

(Amended) 36. The ceramic/metal substrate according to claim [27] 53, wherein the edge reduction is formed by beveling of the respective edge, the beveling forms an angle smaller than 45° with a plane of the ceramic layer.

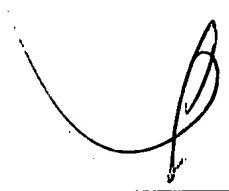
(Amended) 37. The ceramic/metal substrate according to claim [27] 53, wherein the edge reduction is formed by hollows or depressions in a material of the metal surface.

38. The ceramic/metal substrate according to claim 37, wherein the hollows or depressions are formed continuously, and extend to a surface side of the ceramic layer adjacent to the metal surface.

39. The ceramic/metal substrate according to claim 37, wherein the hollows or depressions are formed in such a way that metal from the metal surface remains on the surface side of the ceramic layer adjacent to the metal surface.

(Amended) 40. The ceramic/metal substrate according to claim [27] 53, wherein the edge reduction is formed by a number of hole-like depressions that are arranged as a row of holes.

41. The ceramic/metal substrate according to claim 40, wherein outer and inner depressions form an outer and a second inner row of holes.



42. The ceramic/metal substrate according to claim 40, wherein the depressions have a diameter of approximately 0.5 to 0.6 mm.

43. The ceramic/metal substrate according to claim 40, wherein the depressions forming a single row of holes have a diameter of 0.5 mm, with a width of the edge reduction of approximately 0.8 mm and with a distance of the edge from the predetermined break line of approximately 0.5 mm.

44. The ceramic/metal substrate according to claim 40, wherein the several rows of holes of the outer row of holes have a diameter that is larger than a diameter of the depressions of the inner row of holes, whereby the diameter of the depressions of the outer row of holes is approximately 0.6mm and the diameter of the depressions of the inner row of holes is approximately 0.4 mm and the width of the edge reduction is approximately 1.4 mm.

(Amended) 45. The ceramic/metal substrate according to claim [27] 53, wherein the edge reduction is formed by a groove-shaped depression.

(Amended) 46. The ceramic/metal substrate according to claim [27] 53, wherein the edge reduction is formed by a graduation in at least one partial area.

(Amended) 47. The ceramic/metal substrate according to claim [27] 30, wherein at least in an area of the single substrate on both surfaces of the ceramic layer at least one metal surface is provided for and that the at least one metal surface has, on a first surface area, on a bottom of the ceramic/metal substrate, an edge distance [(d1)] from the adjacent predetermined break

line or its plane which edge distance is smaller than the edge distance [(d2)] of the metal surfaces on the second surface area, on a top of the ceramic/metal substrate.

(Amended) 48. The ceramic/metal substrate according to claim [27] 53, wherein with several substrate areas or single substrates arranged in several rows, two groups of crossing predetermined break lines are formed.

(Amended) 49. The ceramic/metal substrate according to claim [27] 53, wherein on at least one surface area of the ceramic/metal substrate, all edges of the metal surfaces adjacent to a predetermined break line are provided with edge reduction.

(Amended) 50. The ceramic/metal substrate according to claim [27] 53, wherein the metal surfaces on at least one surface area of the ceramic layer has no edge reduction on edges that are adjacent to a group of predetermined break lines.

(Amended) 51. The ceramic/metal substrate according to claim [27] 30, wherein the single substrates [formed by substrate areas] are not provided with components.

(Amended) 52. The ceramic/metal substrate according to claim [27] 53, wherein the single substrates formed by substrate areas are provided with electric components.



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metal surfaces being provided on said substrate areas such, that the metal surfaces on neighbored substrate areas are at a distance from another along said at least one breaking line, said metal surfaces being formed by a metalization which had been bonded to the ceramic layer by a heat process elected from the group consisting of direct bonding or active soldering and by structuring the metalization after bonding,

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that at least one metal surface of each substrate areas has an edge reduction on an edge region adjacent to the predetermined break line and running along this predetermined break line, the edge reduction being of a form that the mass of metal there per volume (specific metal mass) is reduced 10 - 80% along the edge region with reference to the specific metal mass of metal surface outside the edge reduction.

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